

**AMENDMENT TRANSMITTAL LETTER (Large Entity)**

Docket No. YUSO-131

Applicant(s): Hsieh et al.

Group Art Unit: 2818

Examiner: David Vu

Application No.: 10/052,989

Filing Date: November 9, 2001

Invention: Formation of electroplate solder on an organic circuit board for flip chip joints and board to board solder joints

COMMISSIONER FOR PATENTS:


Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated as shown below:

CLAIMS AS AMENDED

	<u>Claims Remaining</u> <u>After Amendment</u>		<u>Highest #</u> <u>Prev. Paid For</u>		<u>Number Extra</u> <u>Claims Present</u>	<u>Rate</u>	<u>Fee</u>
Total Claims	10	-	20	=	0	X \$50	0.00
Indep. Claims	1	-	3	=	0	X \$200	<u>0.00</u>
TOTAL:							\$ -0-

- ☒ No additional fee is required for amendment.
☐ A check in the amount of _____ to cover the filing fee is enclosed.

Date: 3-22-06
Raymond Sun
Reg. No. 35,699**CERTIFICATE OF MAILING**

I hereby certify that the above-identified document is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to "Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450" [37 CFR 1.8(a)] on:

Date: 3-22-06By: Donna Dice
Donna Dice



YUSO-131

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of)	Art Unit: 2818
Hsieh et al.)	
)	Examiner: David Vu
Serial No.: 10/052,989)	
)	
Filing Date: November 9, 2001)	
)	
For: Formation of Electroplate)	
Solder on an Organic Circuit)	
Board for Flip Chip Joints and)	
Board to Board Solder Joints)	

Mail Stop After Final
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AMENDMENT TO FINAL OFFICE ACTION DATED MARCH 3, 2006

In response to the Final Office Action dated March 3, 2006, please enter and consider the following amendments and remarks: